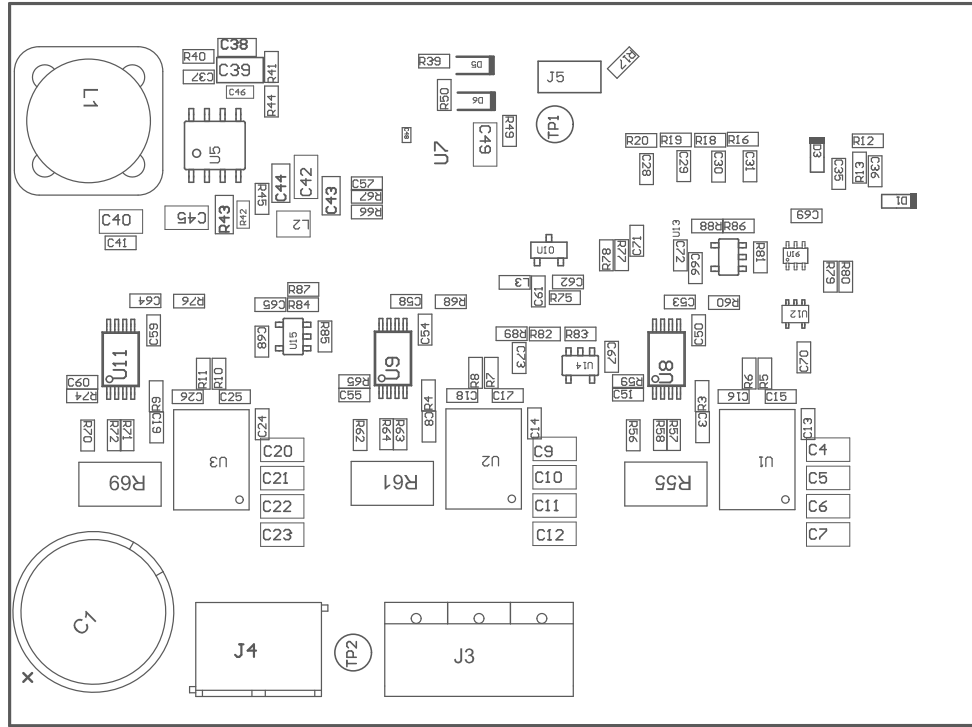


Z22 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.

Z23 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

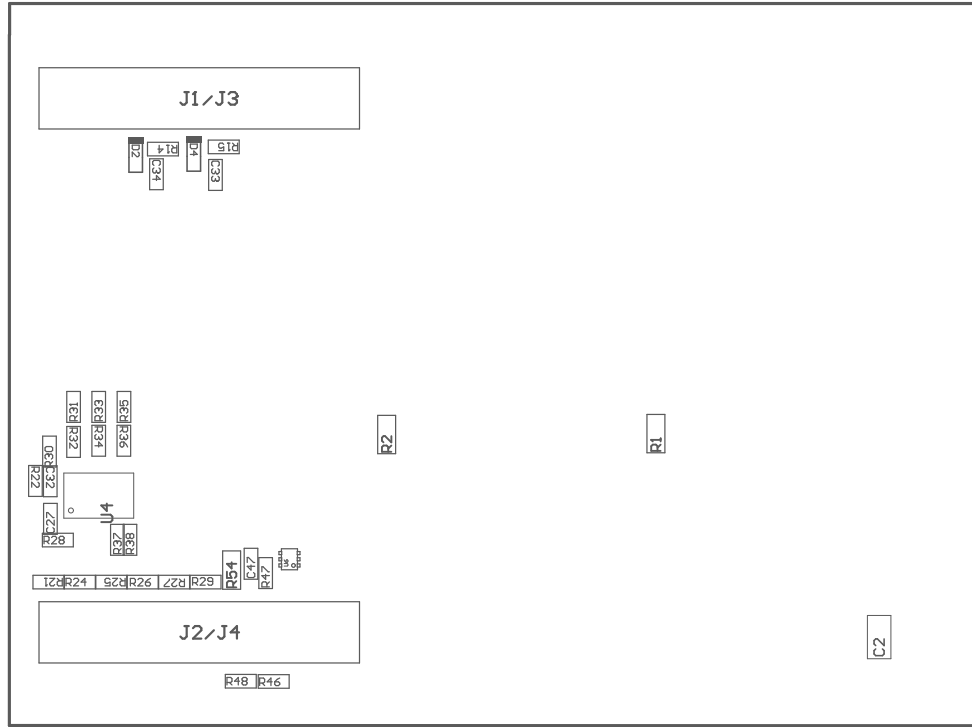
Z24 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
ASSEMBLY VARIANT: 001

JP1

PCB VIEWED FROM TOP SIDE	BOARD #: SENS007	REV: A	SUN REV: Not In VersionControl
	TID #: N/A		
PLOT NAME = Top Assembly Drawing	GENERATED : 6/16/2017 11:39:03 AM		TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: SENS007	REV: A	SUN REV: Not In VersionControl
	TID #: N/A		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 6/16/2017	11:39:04 AM	TEXAS INSTRUMENTS

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